

Product Change Notification - KSRA-27FAPU261

Date:

15 Aug 2019

Product Category:

8-bit Microcontrollers; Touch Controllers; Capacitive Touch Sensors

Affected CPNs:

7

Notification subject:

CCB 3042 Final Notice: Qualification of palladium coated copper with gold flash (CuPdAu) bond in selected products of the 200K wafer technology available in 8L DFN (3x3x0.9mm) package at NSEB assembly site

Notification text:

PCN Status:

Final notification

PCN Type:

Manufacturing Change

Microchip Parts Affected:

Please open one of the icons found in the Affected CPNs section above

NOTE: For your convenience Microchip includes identical files in two formats (.pdf and .xls).

Description of Change:

Qualification of palladium coated copper with gold flash (CuPdAu) bond in selected products of the 200K wafer technology available in 8L DFN (3x3x0.9mm) package at NSEB assembly site

Pre Change:

Using gold (Au) bond wire, 8200T or 8600 die attach material, G770HCD or G700LTD molding compound material and EFTEC-64T lead frame material

Post Change:

Using palladium coated copper with gold flash (CuPdAu) bond wire, 8600 die attach material, G700LTD molding compound material and C194 lead frame material

Pre and Post Change Summary:

	Pre C	hange	Post Change				
Accomply Site	UTAC Thai I	_imited LTD.	UTAC Thai Limited LTD.				
Assembly Site	(NS	EB)	(NSEB)				
Wire material	Au \	Nire	CuPdAu Wire				
Die attach material	8200T	8600	8600				
Molding compound	G770HCD	G700LTD	G700LTD				
material							
Lead frame material	EFTE	C-64T	C194				

Impacts to Data Sheet:

None

Change Impact:

None

Reason for Change:

To improve manufacturability by qualifying CuPdAu bond wire at NSEB assembly site.

Change Implementation Status:

In Progress

Estimated First Ship Date:

March 19, 2018 (date code: 1812)

NOTE: Please be advised that after the estimated first ship date customers may receive pre and post change parts



Time Table Summary:

	August 2017				>	February 2018			March 2018						
Workweek	31	32	33	34	35	/	05	06	07	08	09	10	11	12	13
Initial PCN Issue	Х														
Date	^														
Qual Report										Х					
Availability										^					
Final PCN Issue										Х					
Date										^					
Estimated														Х	
Implementation Date														^	

Method to Identify Change:

Traceability code

Qualification Report:

Please open the attachments included with this PCN labeled as PCN_#_Qual Report **Revision History:**

August 02, 2017: Issued initial notification.

August 31, 2017: Re-issued initial notification to include CCB 3074.

February 19, 2018: Issued final notification. Attached the Qualification Report. Update subject to remove CCB 3074. Revised the affected parts list. Provided estimated first ship date on March 19, 2018.

August 15, 2019: Re-issued final notification to specify the package size (3x3x0.9mm) in the subject and description of change and update the affected CPN list.

The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable products.

Attachment(s):

PCN_KSRA-27FAPU261_Qual Report.pdf

Please contact your local <u>Microchip sales office</u> with questions or concerns regarding this notification.

Terms and Conditions:

If you wish to <u>receive Microchip PCNs via email</u> please register for our PCN email service at our <u>PCN home page</u> select register then fill in the required fields. You will find instructions about registering for Microchips PCN email service in the <u>PCN FAQ</u> section. If you wish to <u>change your PCN profile</u>, including opt out, please go to the <u>PCN home page</u> select login and sign into your myMicrochip account. Select a profile option from the left navigation bar and make the applicable selections. KSRA-27FAPU261 - CCB 3042 Final Notice: Qualification of palladium coated copper with gold flash (CuPdAu) bond in selected products of the 200K wafer technology available in 8L DFN (3x3x0.9mm) package at NSEB assembly site

Affected Catalog Part Numbers (CPN)

MTCH112-I/MF MTCH112T-I/MF MTCH810-I/MF MTCH810T-I/MF PIC12F1501-E/MF PIC12F1501-I/MF PIC12F1501T-E/MF PIC12F1501T-I/MF PIC12F1571-E/MF PIC12F1571-I/MF PIC12F1571T-I/MF PIC12F1572-E/MF PIC12F1572-E/MFC02 PIC12F1572-I/MF PIC12F1572T-E/MFC02 PIC12F1572T-I/MF PIC12F1612-E/MF PIC12F1612-I/MF PIC12F1822-E/MF PIC12F1822-I/MF PIC12F1822-I/MF043 PIC12F1822T-E/MF PIC12F1822T-I/MF PIC12F1840-E/MF PIC12F1840-H/MF PIC12F1840-I/MF PIC12F1840T-E/MF PIC12F1840T-I/MF PIC12LF1501-E/MF PIC12LF1501-I/MF PIC12LF1571-E/MF PIC12LF1571-I/MF PIC12LF1572-E/MF PIC12LF1572-I/MF PIC12LF1572T-I/MF PIC12LF1612-E/MF PIC12LF1612-I/MF PIC12LF1822-E/MF PIC12LF1822-I/MF PIC12LF1822-I/MF023 PIC12LF1822-I/MFC02 PIC12LF1822T-I/MF PIC12LF1840-E/MF PIC12LF1840-I/MF PIC12LF1840T-I/MF